

HOLDING TABLE

ABSTRACT OF THE DISCLOSURE

A holding table for holding a wafer having a device area where a plurality of devices are formed and a peripheral marginal area surrounding the device area on a front side of the wafer, the wafer further having an annular reinforcing portion formed on a back side of the peripheral marginal area. The holding table has an upper surface formed with an annular escape groove for allowing the escape of a laser beam, the annular escape groove being formed so as to correspond to a boundary portion between the device area and the annular reinforcing portion of the wafer held on the upper surface of the holding table, a bottom of the escape groove being tapered and formed with fine asperities for scattering the laser beam.

(Figure 2B)